



# 100% Material Declaration Data Sheet FT64

PK232 (v1.1) March 19, 2012

**Average Weight: 0.2450g**

| Component            | Substance Description  | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|----------------------|------------------------|---------------------------|-------------------------|----------------|--|----------------------------|
| <b>Silicon Die</b>   |                        |                           |                         |                | <b>0.009338</b>                            | <b>3.81%</b>               |
|                      | Silicon (Si)           | 7440-21-3                 | 99.96                   |                | 0.009334                                   |                            |
|                      | Aluminum               | 7429-90-5                 | 0.04                    |                | 0.000004                                   |                            |
| <b>Die Attach</b>    |                        |                           |                         |                | <b>0.001018</b>                            | <b>0.41%</b>               |
|                      | Silver (Ag)            | 7440-22-4                 | 75.00                   |                | 0.000764                                   |                            |
|                      | Epoxy Cresol Novolak   | 29690-82-2                | 24.80                   |                | 0.000252                                   |                            |
|                      | Dibutyl Phthalate      | 84-74-2                   | 0.20                    |                | 0.000002                                   |                            |
| <b>Mold Compound</b> |                        |                           |                         |                | <b>0.149487</b>                            | <b>61.01%</b>              |
|                      | Biphenyl epoxy resin   | 85951-11-6                | 12.00                   |                | 0.017939                                   |                            |
|                      | Phenol Resin           | 9003-35-4                 | 7.00                    |                | 0.010464                                   |                            |
|                      | Quartz                 | 14808-60-7                | 2.50                    |                | 0.003737                                   |                            |
|                      | Silica, vitreous       | 60676-86-0                | 77.00                   |                | 0.115106                                   |                            |
|                      | Carbon Black           | 1333-86-4                 | 0.50                    |                | 0.000747                                   |                            |
|                      | Antimony Trioxide      | 1309-64-4                 | 0.50                    |                | 0.000747                                   |                            |
|                      | Brominated Epoxy Resin | 68541-56-0                | 0.50                    |                | 0.000747                                   |                            |
| <b>Solder Balls</b>  |                        |                           |                         |                | <b>0.017586</b>                            | <b>7.18%</b>               |
|                      | Tin (Sn)               | 7440-31-5                 | 63.00                   |                | 0.011079                                   |                            |
|                      | Lead (Pb)              | 7439-92-1                 | 37.00                   |                | 0.006507                                   |                            |
| <b>Gold Wire</b>     |                        |                           |                         |                | <b>0.000837</b>                            | <b>0.34%</b>               |
|                      | Gold (Au)              | 7440-57-5                 | 100.00                  |                | 0.000837                                   |                            |

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| Component | Substance Description                 | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|-----------|---------------------------------------|---------------------------|-------------------------|----------------|--|----------------------------|
| Substrate |                                       |                           |                         |                | 0.066999                                   | 27.340                     |
| Coating   | Copper (Cu)                           | 7440-50-8                 | 24.92                   |                | 0.023527                                   |                            |
|           | Nickel (Ni)                           | 7440-02-0                 | 14.16                   |                | 0.000195                                   |                            |
|           | Gold (Au)                             | 7440-57-5                 | 0.57                    |                | 0.000119                                   |                            |
| Core      | Fiber Glass                           | 65997-17-3                | 8.49                    |                | 0.016694                                   |                            |
|           | Epoxy resin                           | 9003-36-5                 | 8.49                    |                | 0.009485                                   |                            |
|           | Metal Hydroxide                       | 21645-51-2                | 0.78                    |                | 0.000379                                   |                            |
|           | Bismaleimide                          | 105391-33-1               | 0.08                    |                | 0.005691                                   |                            |
|           | Triazine                              | 25722-66-1                | 0.24                    |                | 0.005691                                   |                            |
| Substrate | Baryum sulfate                        | 7727-43-7                 | 0.03                    |                | 0.000522                                   |                            |
|           | Dipropylene glycol monomethyl         | 34590-94-8                | 3.27                    |                | 0.000052                                   |                            |
|           | Talc containing no asbestiform fibers | 14807-96-6                | 3.35                    |                | 0.000164                                   |                            |
|           | Silica crystalline                    | 14808-60-7                | 0.03                    |                | 0.000023                                   |                            |
|           | 2-(2-Ethoxyethoxy)ethyl Acetate       | 112-15-2                  | 35.12                   |                | 0.002192                                   |                            |
|           | Acrylates derivative                  | 407-47-6                  | 0.29                    |                | 0.002244                                   |                            |
|           | amine compound                        | trade secret              | 1.78                    |                | 0.000021                                   |                            |

## Revision History

The following table shows the revision history for this document.

| Date     | Version | Description of Revisions |
|----------|---------|--------------------------|
| 05/06/08 | 1.0     | Initial Xilinx release.  |
| 03/19/12 | 1.1     | Component CAS# update.   |

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